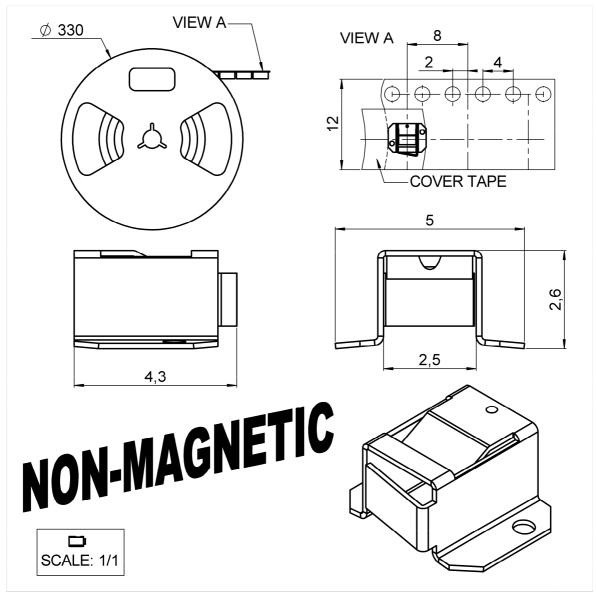
REEL 3300

R107.103.087

Series: UMP



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BERYLLIUM COPPER	TIN

Issue: 0707 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



REEL 3300

R107.103.087

Series: UMP

PACKAGING

Standard	Unit	Other
3300		Contact us

SPECIFICATION

PAQP-VOR-017

ELECTRICAL CHARACTERISTICS

Impedance 50 Ω

Frequency **0-6** GHz VSWR **1.05** + **0.0300** x F(0.000)

Dielectric withstanding voltage Insulation resistance 350 Veff mini 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -40/+55 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

magnetic fields distorsions

<0.5 ppm at 10mm at Bo=1.5 Tesla

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end - N mini
Axial force – Opposite end - N mini
Torque - N.cm mini

Recommended torque

Mating - N.cm Panel nut - N.cm

Mating life 100 Cycles mini

Weight **0,0500** g

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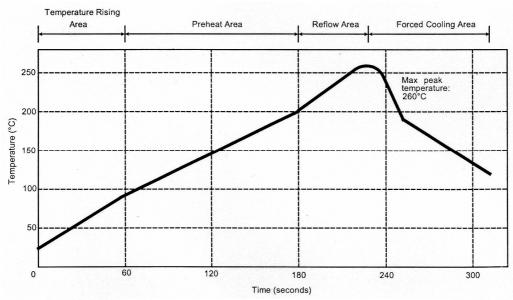
SOLDER PROCEDURE OF UMP RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

NOTE : THE UMP RECEPTACLE AND THE UMP PLUG MUST NOT BE MATED BEFORE COMPLETION OF THIS PROCEDURE.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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UMP SERIES INFORMATION

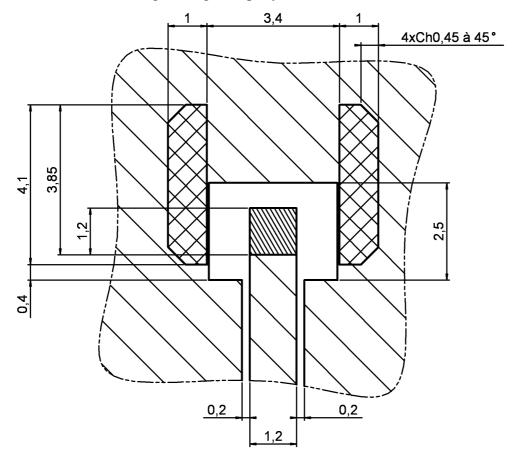
PCB

COPLANAR LINE

Ground and signal are on the same side

Thickness of PCB:1 mm

The material of PCB is glass is glass-epoxy



18µm Cu mini + 7 to 9µm Sn

18μm Cu mini + 7 to 9μm Sn

Ground + varnish

Composite. (Er=4.8)

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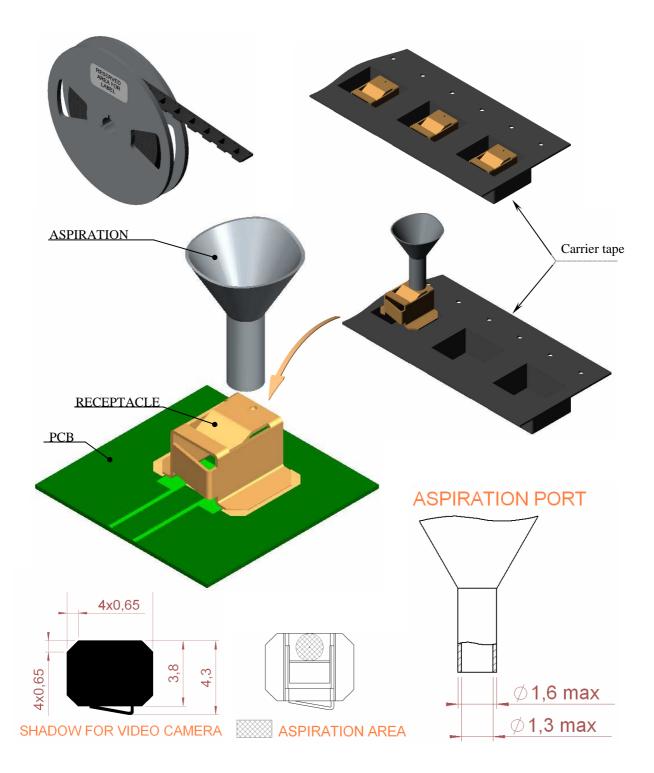


REEL 3300

R107.103.087

Series: UMP

UMP SERIES INFORMATION



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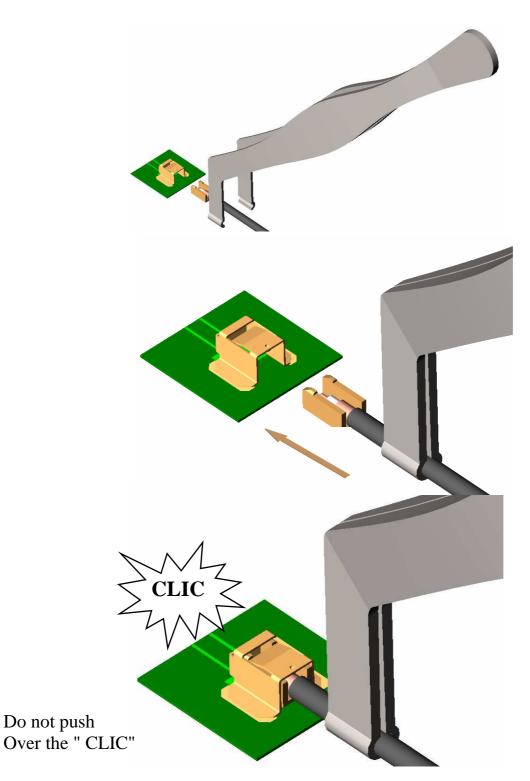


REEL 3300

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Series: UMP

UMP CONNECTING NOTE



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Do not push

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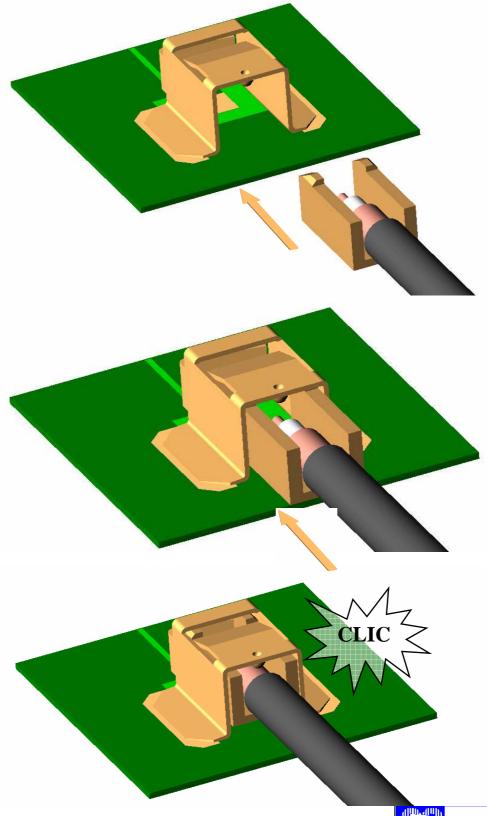


REEL 3300

R107.103.087

Series: UMP

UMP CONNECTING NOTE



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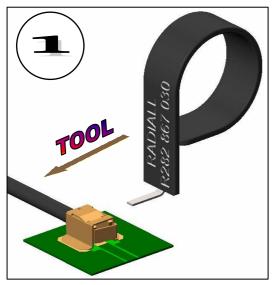


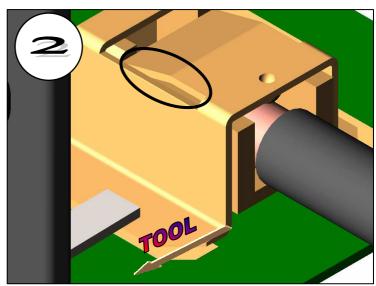
REEL 3300

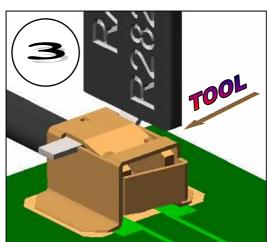
R107.103.087

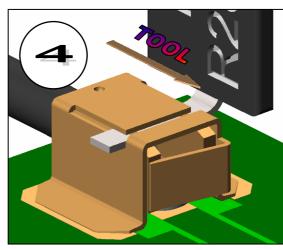
Series: UMP

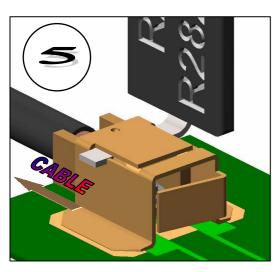
UMP DISCONNECTING NOTE

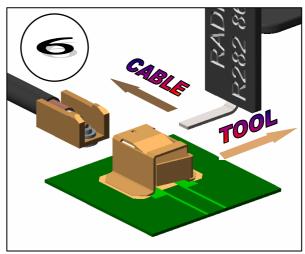












Issue: 0707 A

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